Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

Basic Substance Silica, vitreous (or fused) Epoxy Resin Trade Secret Phenolic Resin Trade Secret Phenolic Resin Trade Secret Trade Secret Carbon Black 1333-86-4 Copper T440-50-8 Nickel T740-02-0 Silver Silicon T440-21-3 Magnesium T7439-95-4 Silver T7440-22-4 Silicon T7440-22-4 Silicon T7440-22-4 Silicon T7440-21-3 Magnesium T7439-95-4 Silver T7440-22-4 Silicon T7440-21-3 Metal oxide Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Gamma-butyrolactone Gold T7440-21-3 Gold T7440-21-3 Tin T7440-31-5	0 TSSOP 4.4mm Matte Tin "Contained In" Sub-Component Mold Compound Mold Compound Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame	% Total Weight 40.562 4.152 2.863 0.143 40.725 1.086	mg/part 31.638 3.238 2.233	ppm 405,620	37.22	(mg) Total			1		
Silica, vitreous (or fused) Epoxy Resin Trade Secret Phenolic Resin Trade Secret Carbon Black Copper 7440-50-8 Nickel 7440-02-0 Silver Silver 7440-22-4 Silicon 7440-21-3 Magnesium 7439-95-4 Silver 7440-22-4 Epoxy resin Trade Secret Metal oxide Trade Secret Gamma-butyrolactone Gold Trade Secret Gold 7440-21-3 Gold 7440-21-3 Gold Trade Secret Trade Secret Trade Secret Metal oxide Trade Secret Gamma-butyrolactone Gold 7440-21-3 Gold 7440-21-3 Gold Trade Secret Trade Secret Gold Trade Secret Trade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-21-3 Gold Trade Secret Tin 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC Compliance with the above EU Directives has been verified via internal design controls, supplier If a chemical substance is absent from the list above, the chemical substance is NOT an intentior incorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the Supplier information is often protected from disclosure as trade secrets and some information in Information is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices	Sub-Component Mold Compound Mold Compound Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame	Weight 40.562 4.152 2.863 0.143 40.725 1.086	31.638 3.238	405,620	37.22	(mg) Total					
Silica, vitreous (or fused) Epoxy Resin Trade Secret Phenolic Resin Trade Secret Carbon Black Copper 7440-50-8 Nickel 7440-02-0 Siliver Silicon 7440-21-3 Magnesium 7439-95-4 Silver Advorged Epoxy resin Trade Secret Trade Secret Trade Secret Trade Secret Trade Secret Trade Secret Silicon 7440-22-4 Silicon 7440-21-3 Magnesium 7439-95-4 Silver Trade Secret Epoxy resin Trade Secret Metal oxide Trade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-57-5 Tin 7440-31-5 Plating on e 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier if a chemical substance is absent from the list above, the chemical substance is NOT an intentior incorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the Supplier information is often protected from disclosure as trade secrets and some information in Information is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices	Mold Compound Mold Compound Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame	40.562 4.152 2.863 0.143 40.725 1.086	31.638 3.238	405,620			Mold Compound	% ot Total Weight	47.72		
Epoxy Resin Trade Secret Phenolic Resin Trade Secret Carbon Black 1333-86-4 Carbon Black 1333-86-4 Copper 7440-50-8 Nickel 7440-02-0 Silver 7440-21-3 Magnesium 7439-95-4 Silver 7440-22-4 Silver 7440-22-4 Silver 7440-22-4 Silver 7440-22-4 Silver 7440-22-4 Epoxy resin Trade Secret Pade Secret Pade Secret Page Secret Pade Secret Pad	Mold Compound Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame	4.152 2.863 0.143 40.725 1.086	3.238				·				
Phenolic Resin Carbon Black 1333-86-4 Copper 7440-50-8 Nickel 7440-02-0 Silver 7440-02-0 Silver 7440-22-4 Silicon 7440-21-3 Magnesium 7439-95-4 Silver 7440-22-4 Epoxy resin Trade Secret Metal oxide Trade Secret Metal oxide Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-21-3 Gold 7440-21-3 Gold 7440-21-3 Gold 7440-31-5 Tin 7440-31-5 Plating on e 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier if a chemical substance is absent from the list above, the chemical substance is NOT an intentior incorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information in Information is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp	Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame	2.863 0.143 40.725 1.086				Silica, vitreous (or fused)	60676-86-0	85.00	ł		
Carbon Black Copper 7440-50-8 Nickel 7440-50-8 Nickel 7440-02-0 Silver 7440-02-0 Silver 7440-21-3 Magnesium 7439-95-4 Silver 7440-22-4 Silver 7440-22-4 Silver 7440-22-4 Silver 7440-22-4 Silver 7440-22-4 Epoxy resin Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-57-5 Tin 7440-31-5 Plating on e 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier If a chemical substance is absent from the list above, the chemical substance is NOT an intentior incorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on thor minformation is provided only as estimates of the average weight of these parts and the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices	Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	0.143 40.725 1.086		41,516 28.632		Epoxy Resin Phenolic Resin	Trade Secret Trade Secret	8.70 6.00	ł		
Copper 7440-50-8 Nickel 7440-02-0 Silver 7440-02-0 Silver 7440-21-3 Magnesium 7439-95-4 Silver 7440-22-4 Silver 7440-22-4 Silver 7440-22-4 Epoxy resin Trade Secret Metal oxide Trade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-31-3 Gold 7440-31-5 Tin 7440-31-5 Plating on e 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier of a chemical substance is absent from the list above, the chemical substance is NOT an intention noroporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You nttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the roughlein information is often protected from disclosure as trade secrets and some information in mformation is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp.	Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	40.725 1.086	0.112	1,432		Carbon Black	1333-86-4	0.30	ł		
Silver 7440-22-4 Silicon 7440-22-4 Silicon 7440-22-4 Silicon 7440-21-3 Magnesium 7439-95-4 Silver 7439-95-4 Silver 7440-22-4 Epoxy resin 74a0-22-4 Epoxy resin 74ad-22-4 Epoxy resin 74ad-21-3 Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-57-5 Tin 7440-31-5 Epiton	Lead Frame Lead Frame Lead Frame	1.086	31.766	407.251		Carbon Black	Total	100.00	1		
Silver Silicon T440-22-4 Silver T440-21-3 Magnesium T439-95-4 Silver T7439-95-4 Silver T7440-22-4 Epoxy resin Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Gamma-butyrolactone 96-48-0 Silicon T440-21-3 Gold T440-57-5 Tin T440-31-5 Plating on e 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier f a chemical substance is absent from the list above, the chemical substance is NOT an intentior ncorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://lul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the Supplier information is often protected from disclosure as trade secrets and some information in normation is provided only as estimates of the average weight of these parts and the average we noclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp.	Lead Frame Lead Frame		0.847	10,861	33.35	(mg) Total	Lead Frame	% of Total Weight	42.76		
Silicon 7440-21-3 Magnesium 7439-95-4 Silver 7439-95-4 Silver 7440-22-4 Epoxy resin Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-57-5 Tin 7440-31-5 Platingone 7440-31-5 Tin 7440-31-5 Platingone 7440-31-5	Lead Frame		0.047	10,001	33.35	(mg) i otai	Lead Frame	% of Total Weight	42.76		
Silicon 7440-21-3 Magnesium 7439-95-4 Silver 7439-95-4 Silver 7439-95-4 Epoxy resin Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Metal oxide Trade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-57-5 Tin 7440-31-5 Platingone 7440-31-5 Tin 7440-31-5 Platingone 7440-31-5	Lead Frame	0.714	0.557	7.137		Copper	7440-50-8	95.24	ł		
Magnesium 7439-95-4 Silver 7440-22-4 Feboxy resin Trade Secret Metal oxide Trade Secret Metal oxide Frade Secret Metal oxide Frade Secret Metal oxide Frade Secret Metal oxide Frade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-31-5 Filming on e 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier of a chemical substance is absent from the list above, the chemical substance is NOT an intention ncorporated's knowledge and belief as of the date of this document, there is no credible reason inny, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the resupplier information is often protected from disclosure as trade secrets and some information in provided only as estimates of the average weight of these parts and the average we include trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with responder provided by Microchip Technology Incorporated and its subsidiaries are contained in		0.192	0.557	1,924		Nickel	7440-50-8	2.54	i		
Silver 7440-22-4 Epoxy resin Trade Secret Metal oxide Trade Secret Gamma-butyrolactone 96-48-0 Silicon 7440-21-3 Gold 7440-21-3 Gold 7440-31-5 Tin 7440-31-5 Plating on e 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier of a chemical substance is absent from the list above, the chemical substance is NOT an intention norporated's knowledge and belief as of the date of this document, there is no credible reason inly, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You attp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as on the completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information in information is provided only as estimates of the average weight of these parts and the average will defend the subsidiaries are contained in the subsi		0.192	0.150	428		Silver	7440-02-0 7440-22-4	2.54 1.67	i		
Epoxy resin Metal oxide Gamma-butyrolactone Gamma-butyrolactone Gaima-butyrolactone Gold Trade Secret Gamma-butyrolactone Silicon 7440-21-3 Gold 7440-57-5 Tin 7440-31-5 Plating one 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC flarch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) compliance with the above EU Directives has been verified via internal design controls, supplier a chemical substance is absent from the list above, the chemical substance is NOT an intention incorporated's knowledge and belief as of the date of this document, there is no credible reason my, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You attp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as on the completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information in formation is provided only as estimates of the average weight of these parts and the average wichude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resprarranties provided by Microchip Technology Incorporated and its subsidiaries are contained in	Die Attach	1.317	1.027	13,172		Silver	7440-22-4 7440-21-3	0.45	i		
Metal oxide Gamma-butyrolactone 96-48-0 96-48-0 Silicon 7440-21-3 Gold 7440-31-5 Fliding on a 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC flarch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) compliance with the above EU Directives has been verified via internal design controls, supplier a chemical substance is absent from the list above, the chemical substance is NOT an intentior incorporated's knowledge and belief as of the date of this document, there is no credible reason may, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You ttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as on the completeness and accuracy of data in this form because it has been compiled based on the repulpiler information is often protected from disclosure as trade secrets and some information in formation is provided only as estimates of the average weight of these parts and the average we include trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp.	Die Attach	0.356	0.278	3,560		Magnesium	7440-21-3	0.45	i		
Gamma-butyrolactone 96-48-0	Die Attach	0.053	0.042	534		iviagriesium	Total	100.00	i .		
Silicon 7440-21-3 Gold 7440-57-5 Tin 7440-57-5 Tin 7440-57-5 Tin 7440-57-5 Tin 7440-31-5 O.0780 g Total O.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier of a chemical substance is absent from the list above, the chemical substance is NOT an intention ncorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Wolding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Wicrochip Technology Incorporated believes the information in this form concerning substances on their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information in mormation is provided only as estimates of the average weight of these parts and the average wenclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp.	Die Attach	0.053	0.042	534	1.39	() T .(.)	Die Attach	% of Total Weight	1.78		
Gold 7440-57-5 Tin 7440-31-5 Plating on a 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier of a chemical substance is absent from the list above, the chemical substance is NOT an intention ncorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances on their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the r Supplier information is often protected from disclosure as trade secrets and some information in mormation is provided only as estimates of the average weight of these parts and the average we include trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp.			3.658		1.39	(mg) Total			1./8		
Tin 7440-31-5 Plating on a 0.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier f a chemical substance is absent from the list above, the chemical substance is NOT an intention noroprorated's knowledge and belief as of the date of this document, there is no credible reason tany, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You nttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as on he completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information in information is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with responderance in the provided by Microchip Technology Incorporated and its subsidiaries are contained in	Chip (Die)	4.690 0.540	0.421	46,900 5.400		Silver	7440-22-4	74.00	i		
O.0780 g Total This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC Alarch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier of a chemical substance is absent from the list above, the chemical substance is NOT an intention incorporated's knowledge and belief as of the date of this document, there is no credible reason inny, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the full provided only as estimates of the average weight of these parts and the average we include trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp	Wire Bond		1.958	25.100		Epoxy resin Metal oxide	Trade Secret Trade Secret	20.00 3.00	i		
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and internal design controls, supplier if a chemical substance is NOT an intention (corporated's knowledge and belief as of the date of this document, there is no credible reason in (in), is not below the threshold of regulatory concern for any regulatory scheme world-wide. (Indich 2015) Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You (Introl/Inde) You (Indich 2015) You (Indi	rnal leads (pins) - Matte Tin / annealed at 150°C for 1 hou TOTAL		78.000	1.000.000			96-48-0	3.00	i		
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) (Indrch 2015) and internal design controls, supplier if a chemical substance is NOT an intention (corporated's knowledge and belief as of the date of this document, there is no credible reason in (in), is not below the threshold of regulatory concern for any regulatory scheme world-wide. (Indich 2015) Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You (Introl/Inde) You (Indich 2015) You (Indi		3: 100.000	70.000	1,000,000		Gamma-butyrolactone	96-48-0 Total	100.00	1		
March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) Compliance with the above EU Directives has been verified via internal design controls, supplier of a chemical substance is absent from the list above, the chemical substance is NOT an intention norporated's knowledge and belief as of the date of this document, there is no credible reason in our, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Moldling compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You outp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride ond certain "reels" may be made from PVC plastic. Alicrochip Technology Incorporated believes the information in this form concerning substances on their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information in onformation is provided only as estimates of the average weight of these parts and the average w conclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp							lotai	100.00			
is a chemical substance is absent from the list above, the chemical substance is NOT an intention neorporated's knowledge and belief as of the date of this document, there is no credible reason inly, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the resupplier information is often protected from disclosure as trade secrets and some information information is provided only as estimates of the average weight of these parts and the average we include trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resprayraranties provided by Microchip Technology Incorporated and its subsidiaries are contained in	his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 larch 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)					Total (mg)	Chip (Die)	% of Total Weight	4.69		
ncorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Wolding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You nttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Wicrochip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the ruspiplier information is often protected from disclosure as trade secrets and some information mormation is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in	ompliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.					Doped Silicon	7440-21-3	100.00			
ncorporated's knowledge and belief as of the date of this document, there is no credible reason any, is not below the threshold of regulatory concern for any regulatory scheme world-wide. Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You nttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as of he completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information monformation is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Microchip Technology Incorporated does not provide any warranty, express or implied, with resp warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in	· · · · · · · · · · · · · · · · · · ·						Total	100.00	ı		
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride and certain "reels" may be made from PVC plastic. Alicrochip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as on the completeness and accuracy of data in this form because it has been compiled based on the resupplier information is often protected from disclosure as trade secrets and some information in information is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices Alicrochip Technology Incorporated does not provide any warranty, express or implied, with resp varranties provided by Microchip Technology Incorporated and its subsidiaries are contained in	. ,			ubstance, if	0.42	(mg) Total	Wire Bond	% of Total Weight	0.54		
Indicrochip Technology Incorporated believes the information in this form concerning substances in their original packing materials is true and correct to the best of its knowledge and belief, as one completeness and accuracy of data in this form because it has been compiled based on the resupplier information is often protected from disclosure as trade secrets and some information in information is provided only as estimates of the average weight of these parts and the average windled trace levels of dopants, metals, and non-metal materials contained within silicon devices discrochip Technology Incorporated does not provide any warranty, express or implied, with resp varranties provided by Microchip Technology Incorporated and its subsidiaries are contained in						(mg) rotal	Wife Bolid	70 or rotal Weight	0.04		
In their original packing materials is true and correct to the best of its knowledge and belief, has of the completeness and accuracy of data in this form because it has been compiled based on the supplier information is often protected from disclosure as trade secrets and some information in mormation is provided only as estimates of the average weight of these parts and the average winclude trace levels of dopants, metals, and non-metal materials contained within silicon devices discretionable of the provided provided to the provided and warranty, express or implied, with responsive provided by Microchip Technology Incorporated and its subsidiaries are contained in	The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.					Doped Gold	7440-57-5	100.00			
he completeness and accuracy of data in this form because it has been compiled based on the r Supplier information is often protected from disclosure as trade secrets and some information in information is provided only as estimates of the average weight of these parts and the average w include trace levels of dopants, metals, and non-metal materials contained within silicon devices wicrochip Technology Incorporated does not provide any warranty, express or implied, with resp warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in	Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices						Total	100.00			
warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in	nges provided in Material Safety Data S	heets provided by ct assemblers and	raw material raw material	suppliers. suppliers.							
icrochip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in icrochip's quotations, sales order acknowledgement, and invoices.					1.96	(mg) i otai	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	2.51		
Wicrochip disclaims any duty to notify users of updates or changes to Material Content Declaration to therwise, suffered by users or third parties as a result of the users' reliance on the information for of this Certificate of Compliance for semiconductor products.	ght of anticipated significant toxic met silicon IC) in the finished parts. ct to the information provided in this de					Tin	7440-31-5	100.00			
ssembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at ttp://echa.europa.eu/web/quest/candidate-list-table							Total	100.00			

Au 1:52 PM : 8/17/2015